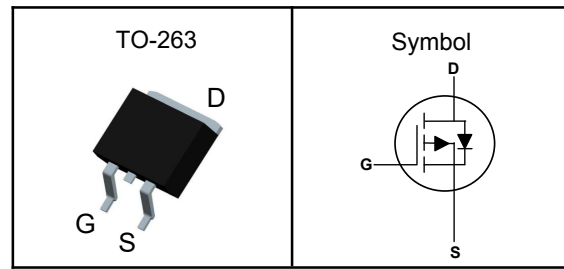


P-Channel Enhancement Mode MOSFET
Features

- Advanced trench cell design
- Low Thermal Resistance
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Motor drivers
- DC - DC Converter

Pin Description


V_{DSS}	-100	V
$R_{DS(ON)-Typ}$	12	m Ω
I_D	-65	A

Absolute Maximum Ratings($T_J=25^{\circ}C$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
V_{DSS}	Drain-Source Voltage	-100	V	
V_{GSS}	Gate-Source Voltage	± 20	V	
T_J	Maximum Junction Temperature	-55 to 150	$^{\circ}C$	
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$	
$I_{DM}^{①}$	Pulse Drain Current Tested	-260	A	
I_D	Continuous Drain Current	$T_C=25^{\circ}C$	-65	A
P_D	Maximum Power Dissipation	$T_C=25^{\circ}C$	125	W
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	60	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.5mH	180	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	16	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1	$^{\circ}C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 $^{\circ}C$.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

**P-Channel Enhancement Mode MOSFET****Electrical Characteristics** ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-80V, V_{GS}=0V$	---	---	-1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	---	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_D=-15A$	---	12	15	m Ω
		$V_{GS}=-4.5V, I_D=-10A$	---	14	18	m Ω
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=-30V, \text{Freq.}=1\text{MHz}$	---	10103	---	pF
C_{oss}	Output Capacitance		---	593	---	
C_{rss}	Reverse Transfer Capacitance		---	161	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=-10V, V_{DD}=-50V, I_D=-15A, R_G=1\Omega$	---	35	---	nS
T_r	Turn-on Rise Time		---	36	---	
$T_{d(off)}$	Turn-off Delay Time		---	169	---	
T_f	Turn-off Fall Time		---	51	---	
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DD}=-50V, I_D=-15A$	---	176	---	nC
Q_{gs}	Gate-Source Charge		---	20	---	
Q_{gd}	Gate-Drain Charge		---	60	---	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	$I_S=-15A, V_{GS}=0V$	---	---	-1.2	V

Note ④: Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

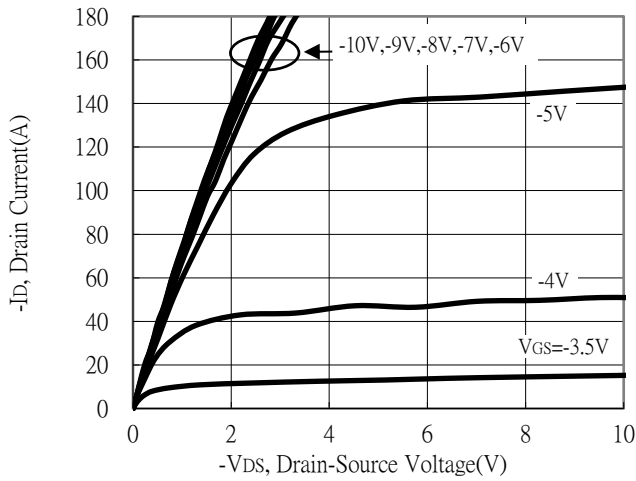
Note ⑤: Guaranteed by design, not subject to production testing.



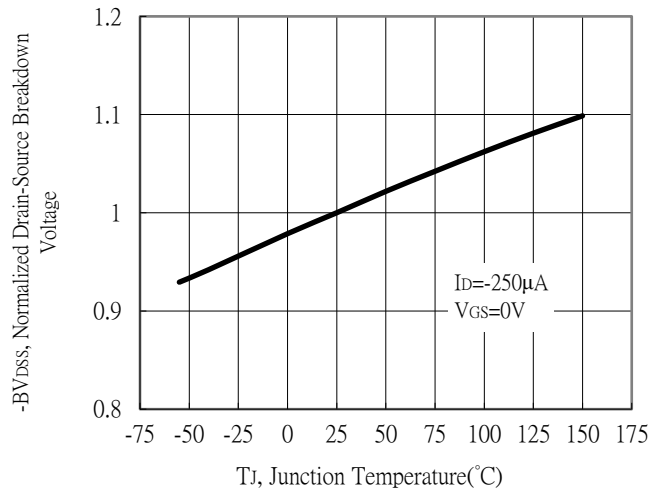
P-Channel Enhancement Mode MOSFET

Typical Characteristics

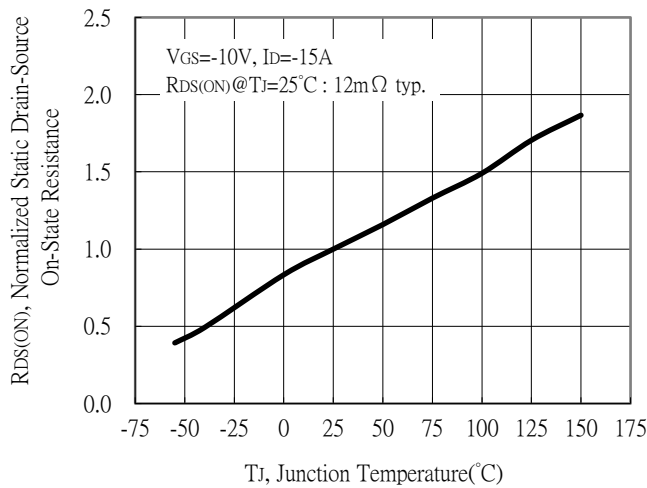
Typical Output Characteristics



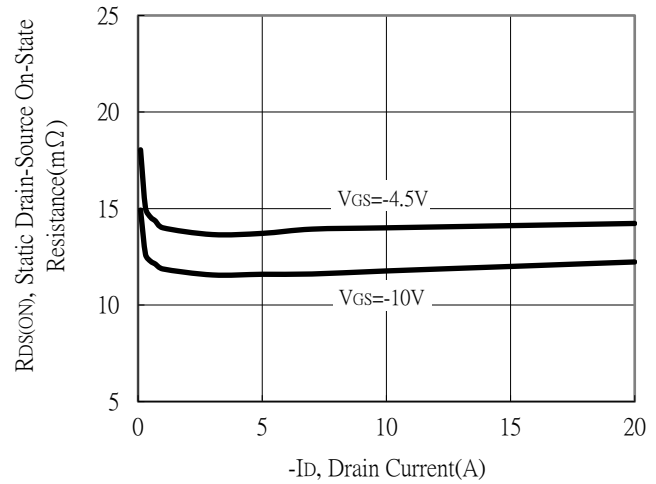
Breakdown Voltage vs Ambient Temperature



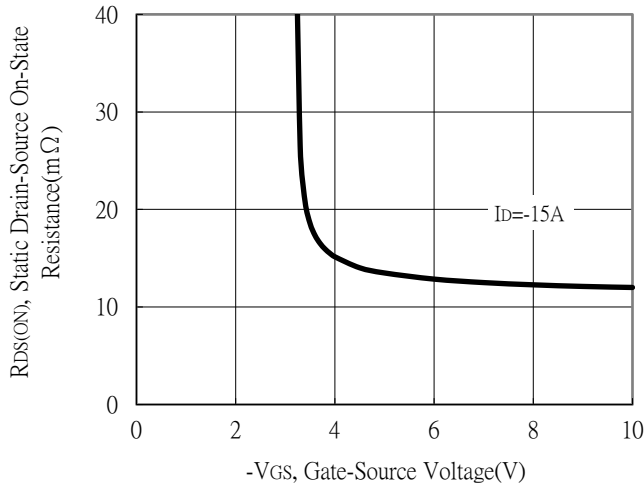
Drain-Source On-State Resistance vs Junction Temperature



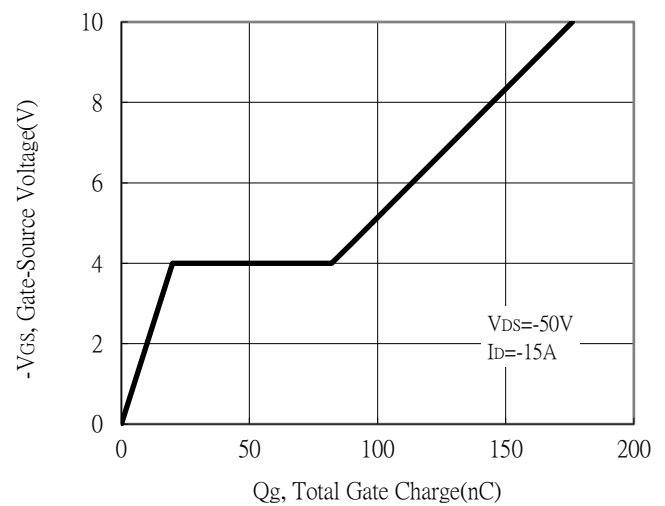
Static Drain-Source On-State resistance vs Drain Current



Static Drain-Source On-State Resistance vs Gate-Source Voltage

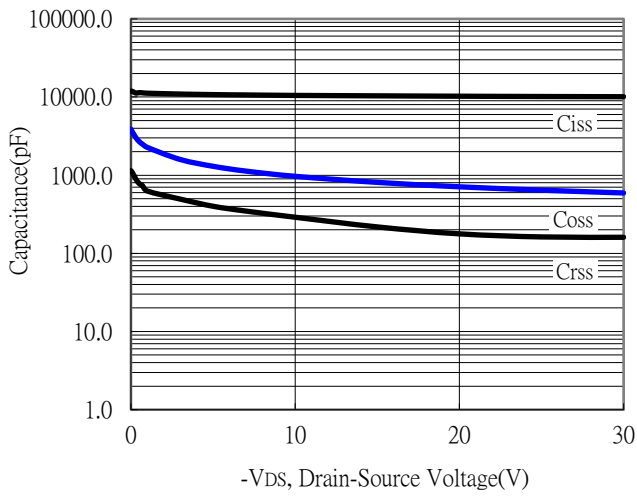


Gate Charge Characteristics

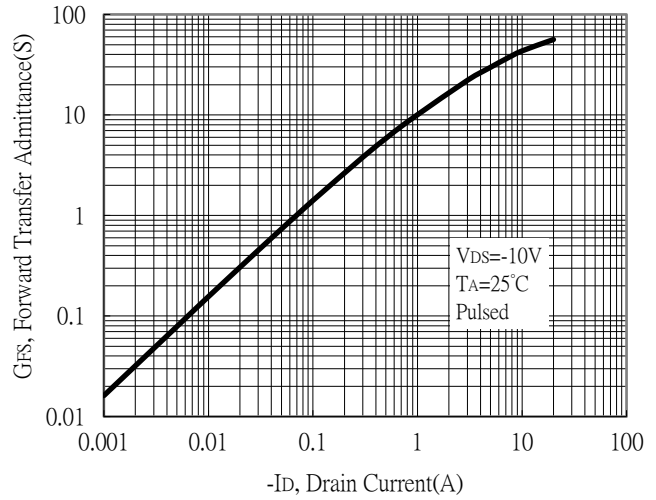


P-Channel Enhancement Mode MOSFET

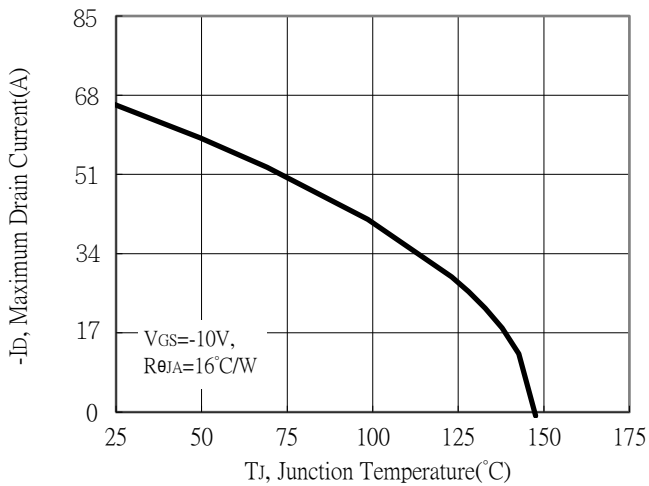
Capacitance vs Drain-to-Source Voltage



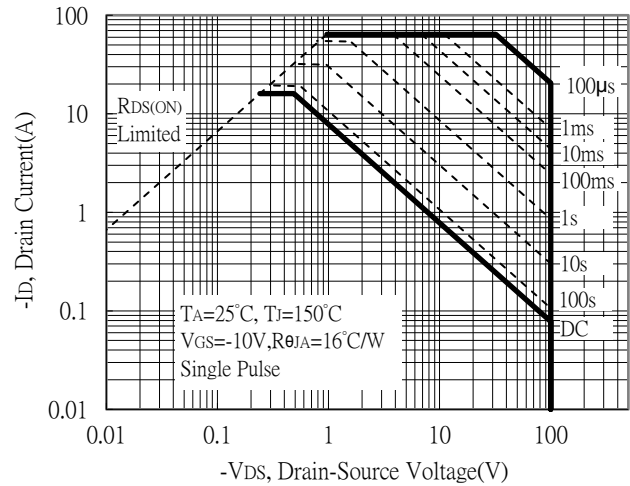
Forward Transfer Admittance vs Drain Current



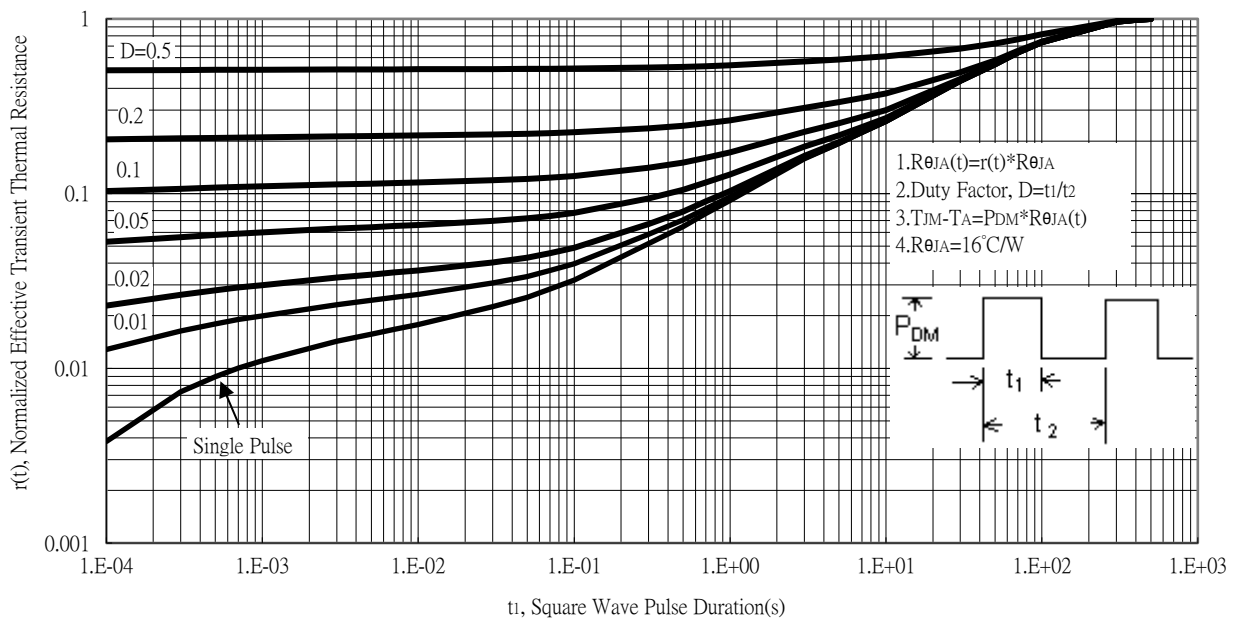
Maximum Drain Current vs Junction Temperature



Maximum Safe Operating Area



Transient Thermal Response Curves



P-Channel Enhancement Mode MOSFET

TO-263 Package Outline Data

